



LOW CAPACITANCE BIDIRECTIONAL TVS DIODE

Features

- Provides ESD Protection per IEC 61000-4-2 Standard: Air ±30kV, Contact ±30kV
- Ultra Low Profile (0.4mm), Ideal for Thin Portable Electronics
- 1 Channel of ESD Protection
- High Peak Pulse Current per IEC 61000-4-5 Standard
- Low Channel Input Capacitance
- Typically Used in Cellular Handsets, Portable Electronics, Communication Systems, Computers and Peripherals
- Lead Free/RoHS Compliant (Note 1)
- Halogen and Antimony Free "Green" Device (Notes 2 & 3)

Mechanical Data

- Case: X2-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.001 grams (approximate)

X2-DFN1006-2



Bottom View



Device Schematic

Ordering Information (Note 4)

| Part Number | Case | Packaging |
|-----------------|--------------|--------------------|
| DESD5V0S1BLD-7B | X2-DFN1006-2 | 10,000/Tape & Reel |

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. No purposely added lead.
- 2. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information

R8

R8 = Product Type Marking Code Line Denotes Pin 1

1 of 1

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Maximum Ratings @T_A = 25°C unless otherwise specified

| Characteristic | Symbol | Value | Unit | Conditions |
|------------------------------------|--------------------------|-------|------|------------------------|
| Peak Pulse Power Dissipation | P_PP | 130 | W | 8/20μs, Per Fig. 1 |
| Peak Pulse Current | I _{PP} | 12 | Α | 8/20μs, Per Fig. 1 |
| ESD Protection – Contact Discharge | V _{ESD_Contact} | ±30 | kV | IEC 61000-4-2 Standard |
| ESD Protection – Air Discharge | V_{ESD_Air} | ±30 | kV | IEC 61000-4-2 Standard |

Thermal Characteristics

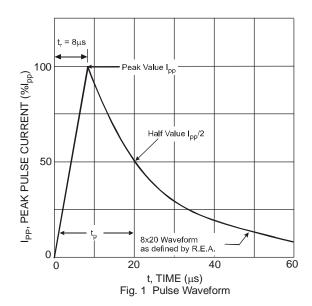
| Characteristic | Symbol | Value | Unit |
|--|-----------------------------------|-------------|------|
| Package Power Dissipation (Note 5) | P_{D} | 250 | mW |
| Thermal Resistance, Junction to Ambient (Note 5) | $R_{	heta JA}$ | 500 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -65 to +150 | °C |

Electrical Characteristics @TA = 25°C unless otherwise specified

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Conditions |
|----------------------------------|------------------|-----|-----|-----|------|----------------------------------|
| Reverse Standoff Voltage | V_{RWM} | - | - | 5 | V | - |
| Channel Leakage Current (Note 6) | I _{RM} | - | 5 | 100 | nA | V _{RWM} = 5V |
| Clamping Voltage | | - | - | 10 | V | $I_{PP} = 1A, t_p = 8/20 \mu S$ |
| Clamping voltage | V _{CL} | - | - | 14 | | $I_{PP} = 12A, t_p = 8/20\mu S$ |
| Breakdown Voltage | V_{BR} | 5.5 | - | 9.5 | V | $I_R = 1 mA$ |
| Differential Resistance | R _{DIF} | - | 0.4 | - | Ω | $I_R = 10A$, $t_p = 8/20 \mu S$ |
| Channel Input Capacitance | Ст | - | 35 | 45 | pF | $V_R = 0V$, $f = 1MHz$ |

Notes:

- 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.
- 6. Short duration pulse test used to minimize self-heating effect.



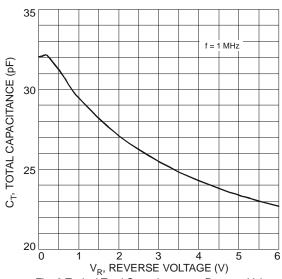
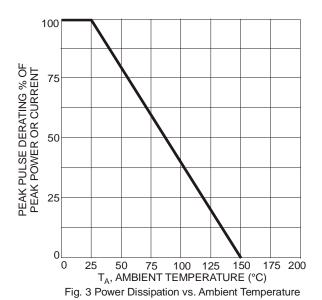
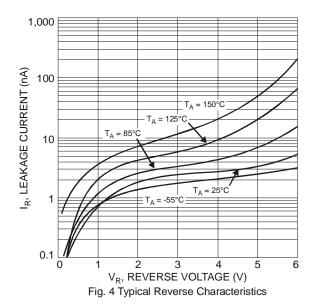


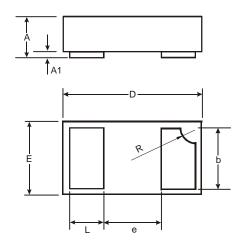
Fig. 2 Typical Total Capacitance vs. Reverse Voltage







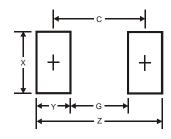
Package Outline Dimensions



| X2-DFN1006-2 | | | | | |
|----------------------|------|-------|------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 0.34 | 0.4 | 0.37 | | |
| A1 | 0 | 0.05 | 0.03 | | |
| b | 0.45 | 0.55 | 0.50 | | |
| D | 0.95 | 1.075 | 1.00 | | |
| E | 0.55 | 0.675 | 0.60 | | |
| E | | | 0.40 | | |
| L | 0.20 | 0.30 | 0.25 | | |
| R | 0.05 | 0.15 | 0.10 | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

DESD5V0S1BLD



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 1.1 |
| G | 0.3 |
| Х | 0.7 |
| Y | 0.4 |
| С | 0.7 |



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